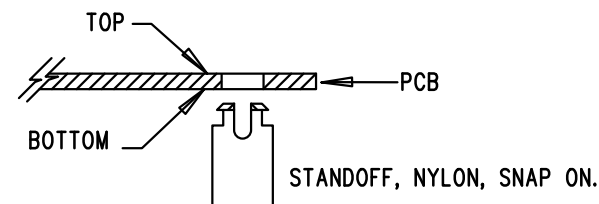



REVISION HISTORY				
ECO	REV	DESCRIPTION	APPR	DATE
	1	PRODUCTION	YS	03-22-16

NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL 4 STANDOFFS AS SHOWN.



8. SET SHUNTS TO DEFAULT SETTINGS
JP1 WP = OFF
JP2 EE WP = ON
9. INSURE MANUFACTURERS DUMMY PACKAGE IS INSTALLED PRIOR TO SOLDERING SOCKET TO PCB

APPROVALS		 <div> 1630 MCCARTHY BLVD MILPITAS, CA 95035 PH: (408)432-1900 www.linear.com LTC CONFIDENTIAL- FOR CUSTOMER USE ONLY </div>		
PCB DES.	LT			
APP ENG.	YS			
		TITLE: TOP ASSEMBLY DRAWING		
		PROGRAMMING BOARD FOR LTC3886UKG		
		SIZE	IC NO.	REV.
		N/A	LTC3886UKG DEMO CIRCUIT 2277A	1
SCALE = NONE		FILENAME: DC2277A-1.PCB		SHT 1 OF 2